

Description

The TD816 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic DIP4 package with different lead forming options.

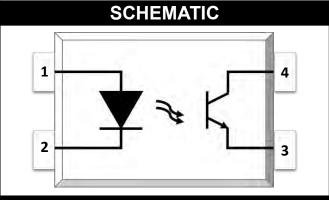
With the robust coplanar double mold structure, TD816 series provide the most stable isolation feature.

Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range 55 °C to 110 °C
- REACH compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
 - UL UL1577
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - cUL- CSA Component Acceptance
 Service Notice No. 5A

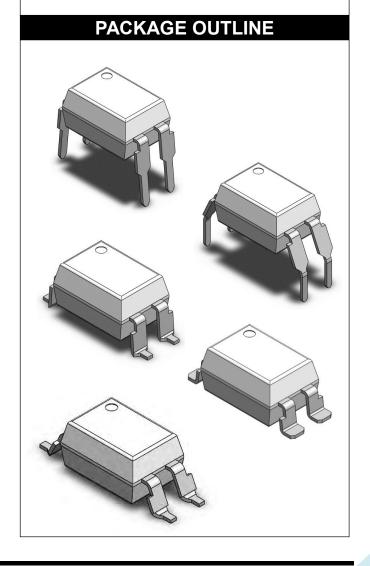
Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment



PIN DEFINITION

- 1. Anode
- 2. Cathode
- 3. Emitter
- 4. Collector





ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	VALUE	UNIT	NOTE			
INPUT							
Forward Current	I _F	60	mA				
Peak Forward Current	I _{FP}	1	Α	1			
Reverse Voltage	V _R	6	V				
Input Power Dissipation	Pı	100	mW				
OUTPUT							
Collector - Emitter Voltage	V _{CEO}	80	V				
Emitter - Collector Voltage	V _{ECO}	6	V				
Collector Current	Ic	50	mA				
Output Power Dissipation	Po	150	mW				
COMMON							
Total Power Dissipation	Ptot	200	mW				
Isolation Voltage	Viso	5000	Vrms	2			
Operating Temperature	Topr	-55~110	°C				
Storage Temperature	Tstg	-55~125	°C				
Soldering Temperature	Tsol	260	°C				

Note 1. 100µs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = $40 \sim 60\%$



	ELECT	RICAL OF	PTICA	L CHA	ARAC	TER	ISTICS at Ta=25°C	
PARAM	ETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT								
Forward \	/oltage	V _F	-	1.24	1.4	V	IF=10mA	
Reverse (Current	I _R	-	-	10	μΑ	VR=6V	
Input Capa	Input Capacitance		-	10	_	pF	V=0, f=1kHz	
				OUT	PUT			
Collector Da	rk Current	I _{CEO}	-	_	100	nA	VCE=20V, IF=0	
Collector- Breakdown		BV _{CEO}	80	-	-	V	IC=0.1mA, IF=0	
Emitter-C Breakdown		BV _{ECO}	6	-	-	V	IE=0.1mA, IF=0	
TRANSFER CHARACTERISTICS								
	TD816		50	-	600			
	TD816A		80	-	160			
Current	TD816B		130	-	260		IF=5mA, VCE=5V	
Transfer	TD816C	CTR	200	-	400	%		
Ratio	TD816D		300	1	600			
	TD816E		100	ı	200			
	TD816F		150	_	300			
Collector- Saturation		V _{CE(sat)}	-	0.06	0.2	V	IF=20mA, IC=1mA	
Isolation Resistance		R _{ISO}	10^12	10^14	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance		C _{IO}	-	0.4	1	pF	V=0, f=1MHz	
Response Time (Rise)		tr	-	3	18	μs	VCE=2V, IC=2mA	3
Response T	Response Time (Fall)		-	4	18	μs	RL=100Ω	3
Cut-off Frequency		fc	-	80	-	kHz	VCE=2V, IC=2mA RL=100Ω,-3dB	4

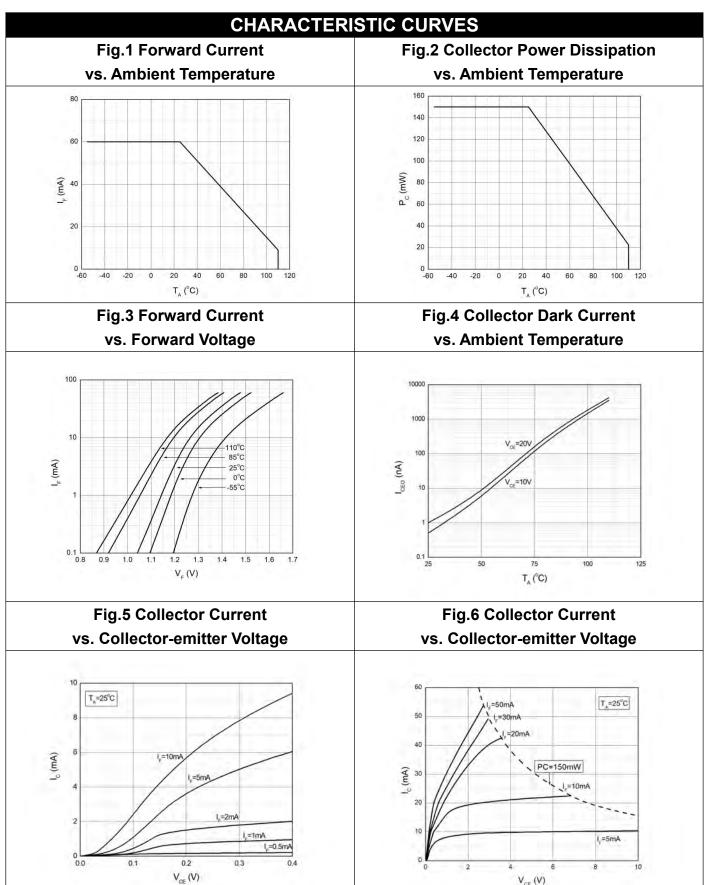
Note 3. Fig.12&13

Note 4. Fig.14



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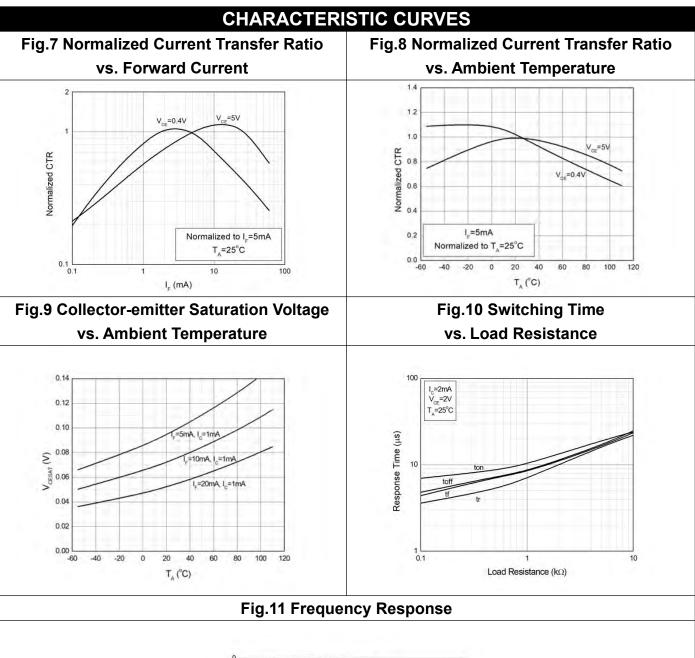
DIP4, DC Input, Photo Transistor Coupler

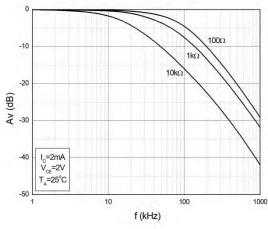


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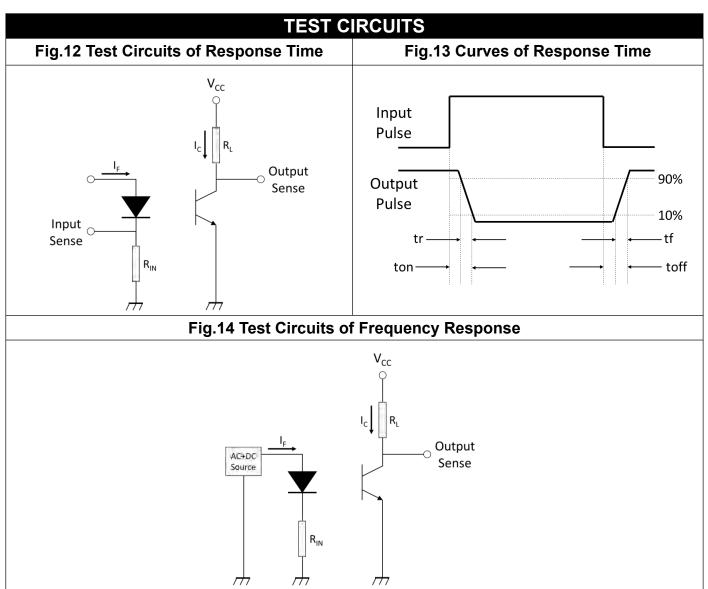
Release Date: 2024/08/12



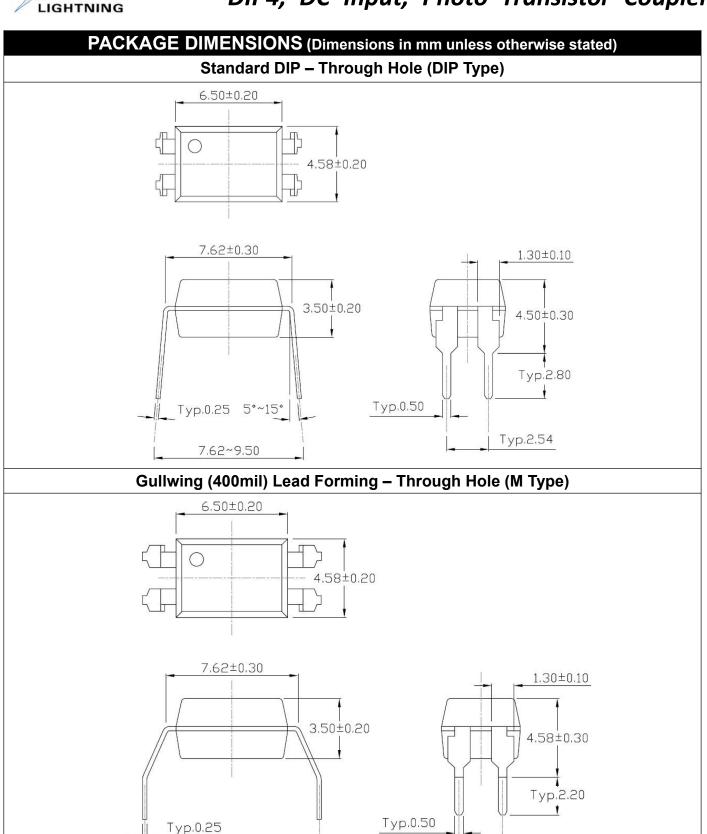










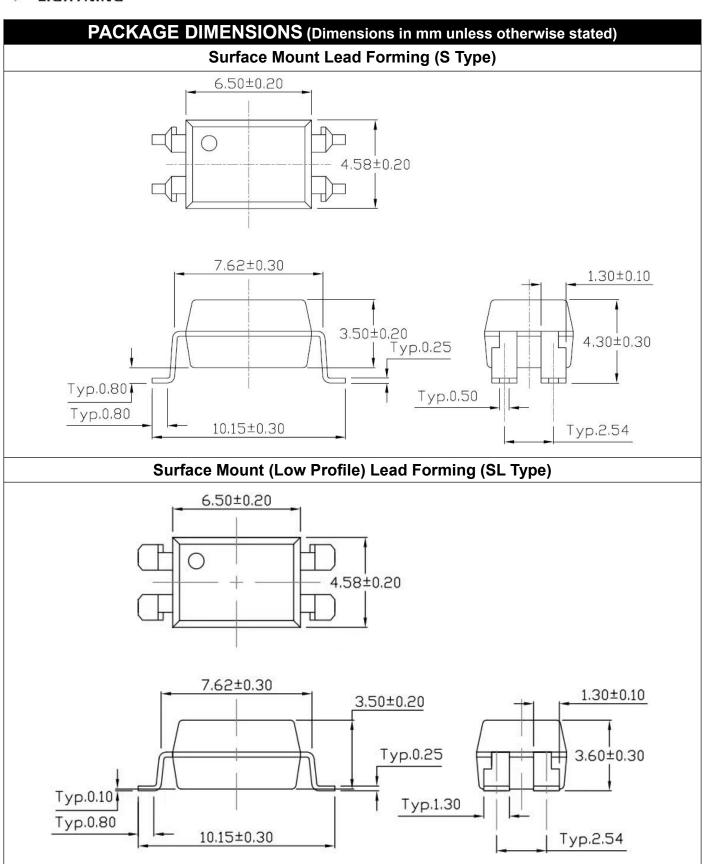


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10.16±0.30

Typ.2.54

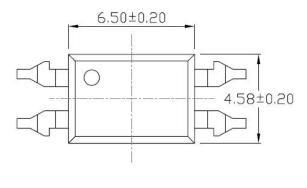


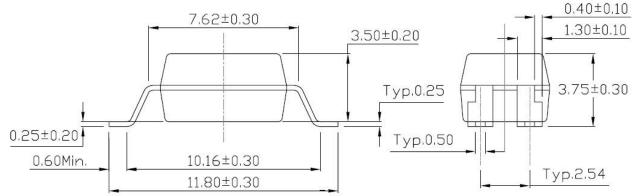




PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

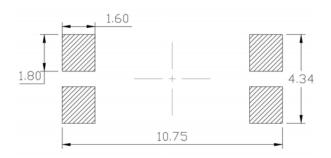
Surface Mount (Gullwing) Lead Forming (SLM Type)



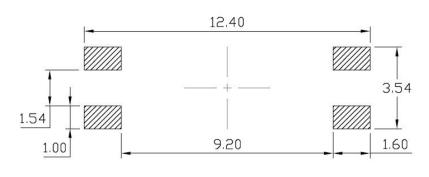


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

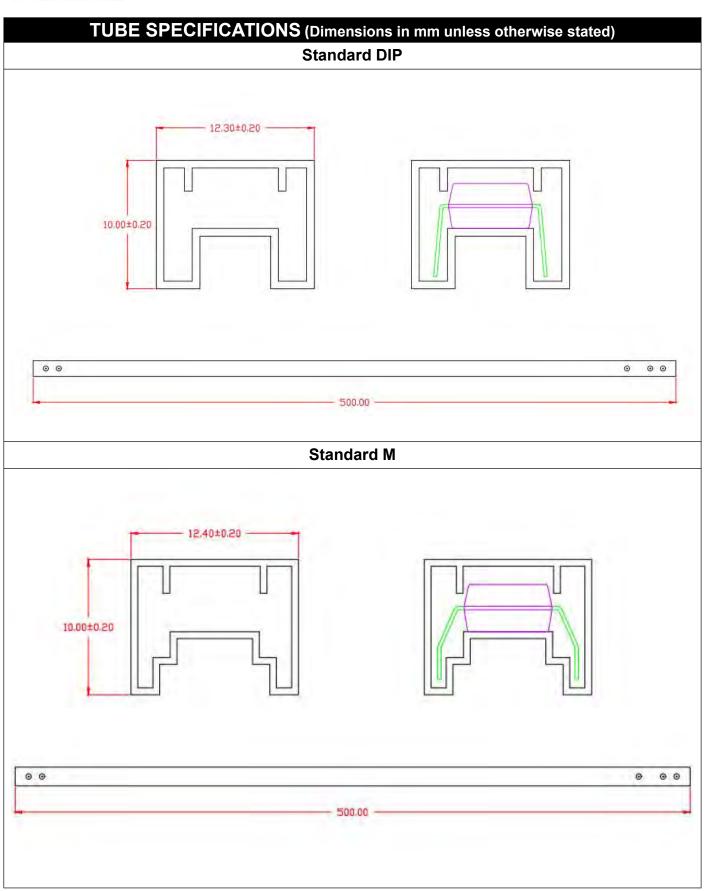
Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming



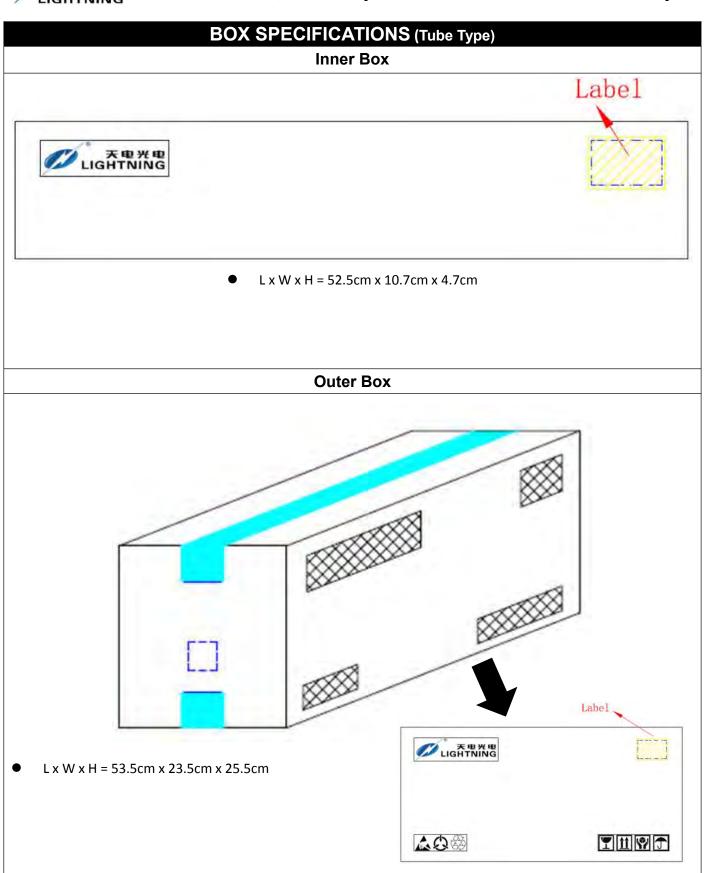
Surface Mount (Gullwing) Lead Forming



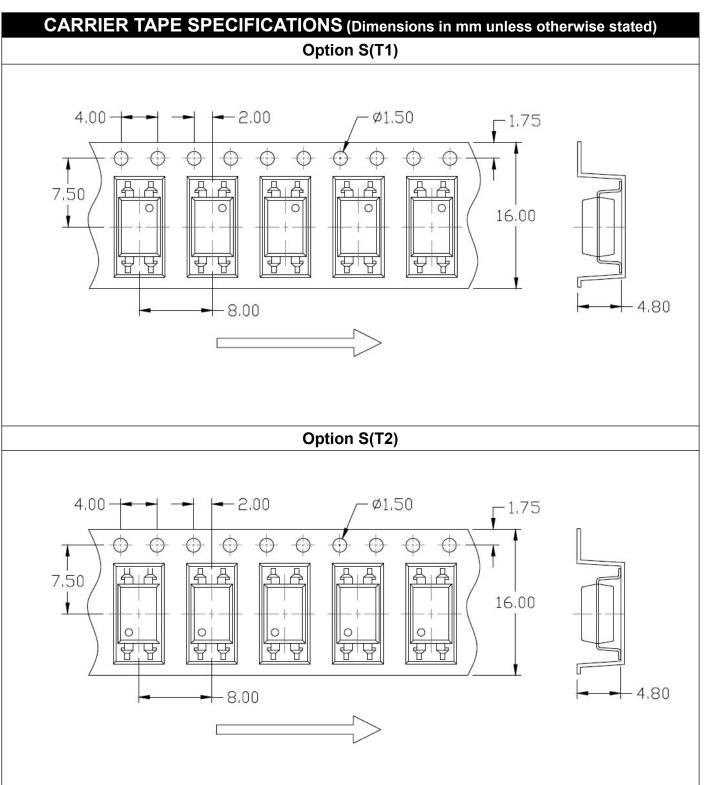




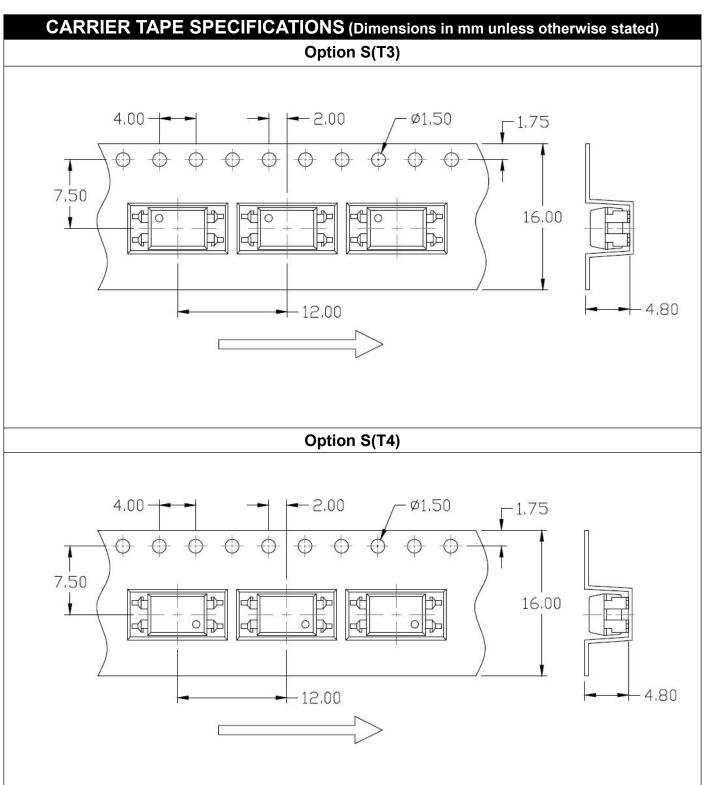




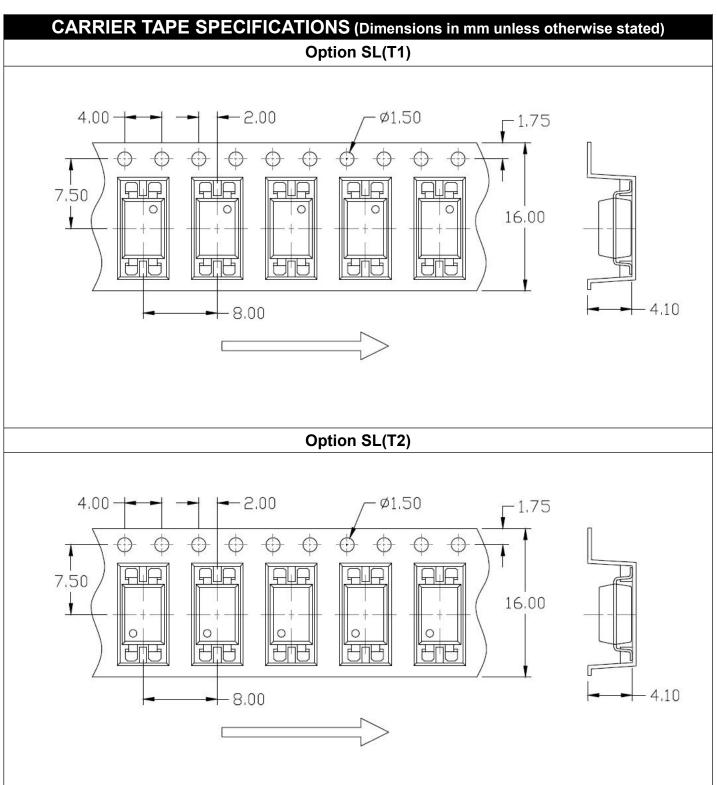




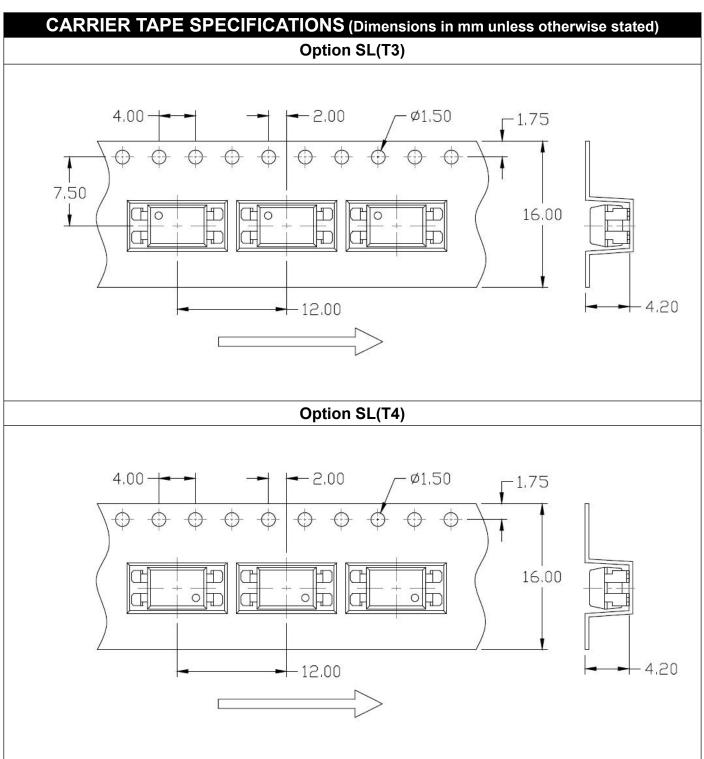




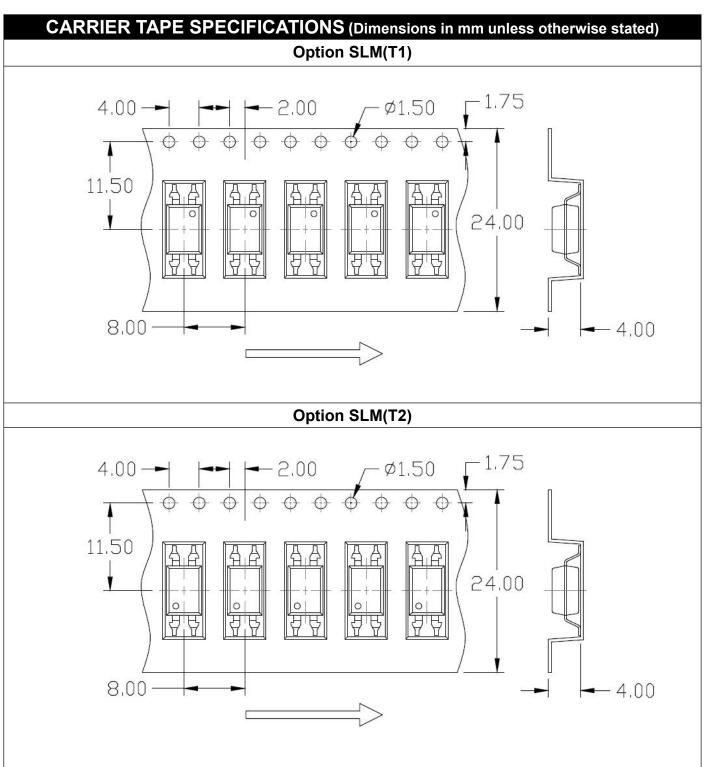




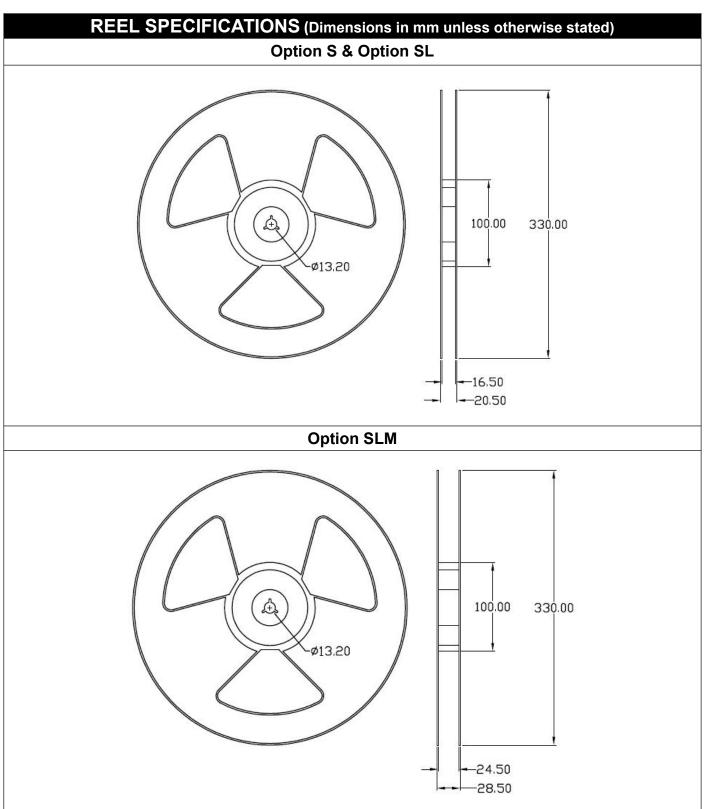




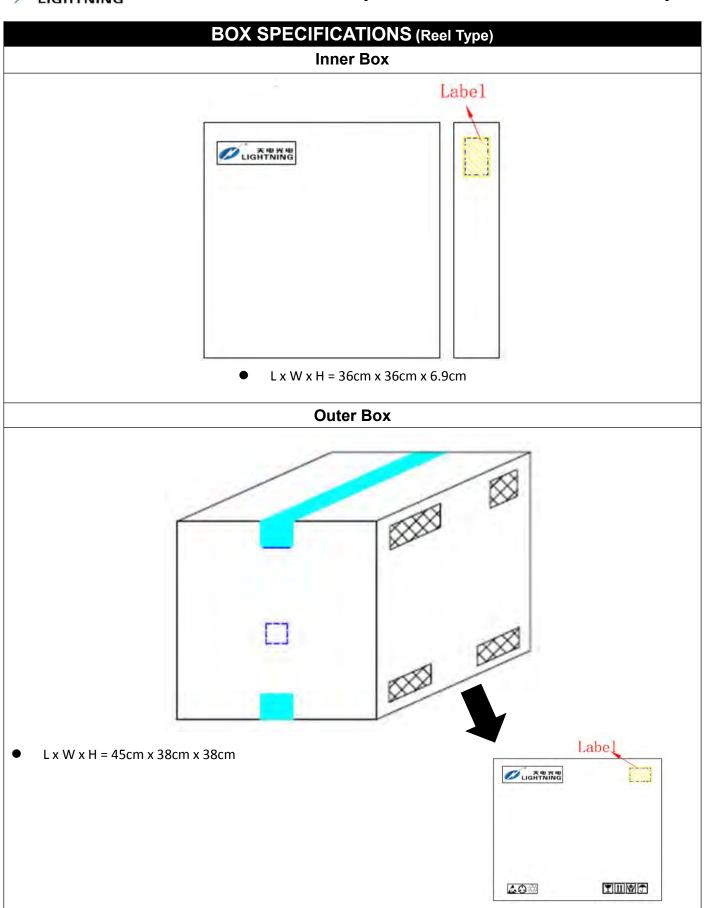












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ORDERING AND MARKING INFORMATION

MARKING INFORMATION



TD : Company Abbr.

816 : Part Number

X : CTR Rank

: VDE Option Υ : Fiscal Year

: Manufacturing Code

ww : Work Week

ORDERING INFORMATION

ORDERING INFORMATION

TD816X(Y)(Z)-GV

TD - Company Abbr.

816 - Part Number

X – Rank (A/B/C/D/E/F or None)

Y – Lead Form Option (M/S/SL/SLM/None)

Z – Tape and Reel Option (T1/T2/T3/T4)

G - Green

V – VDE Option (V or None)

LABEL INFORMATION



lo.: AGXXXXXX

Date Code: XXXX QTY: XXXX PCS









Packing Quantity

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Option	Quantity	Quantity – Inner box	Quantity – Outer box		
None	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 32k Units		
М	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 32k Units		
S(T1)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units		
S(T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units		
S(T3)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units		
S(T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units		
SL(T1)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units		
SL(T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units		
SL(T3)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units		
SL(T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units		
SLM(T1)	1500 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box = 15k Units		
SLM(T2)	1500 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box = 15k Units		

IPC-020d-5-1



DIP4, DC Input, Photo Transistor Coupler

REFLOW INFORMATION REFLOW PROFILE Supplier T_p ≥ T_c User T_p ≤ T_c User T_p ≤ T_c User t_p → T_c -5°C Max. Ramp Up Rate = 3°C/s Max. Ramp Down Rate = 6°C/s T_{smax} Preheat Area T_{smin} Preheat Area T_{smin}

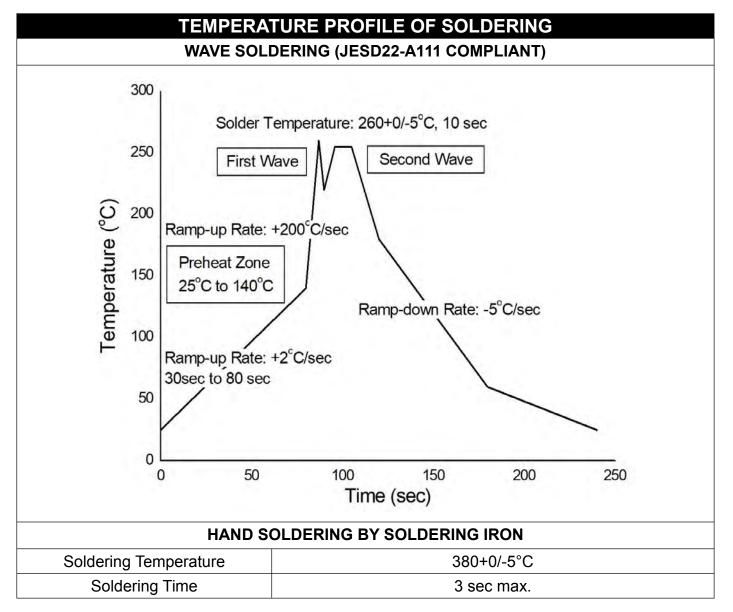
Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Time ⇒

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Time 25°C to Peak





- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.



DISCLAIMER

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- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
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- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact LIGHTNING sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary
 over time. All operating parameters, including typical parameters, must be validated in each
 customer application by the customer's technical experts. Product specifications do not expand or
 otherwise modify LIGHTNING's terms and conditions of purchase, including but not limited to the
 warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.